



Title of Change:	Copper wire conversion for LV8702V												
Proposed first ship date:	18 January 2017												
Contact information:	Contact your local ON Semiconductor Sales Office or < Tsutomu.Shimazaki@onsemi.com > < Takashi.Harashima@onsemi.com>< Takeshi2.Hoshino@onsemi.com>< Kazumi.Onda@onsemi.com> < Shinya.Okada@onsemi.com>< Yoshiyuki.Nunokawa@onsemi.com>												
Samples:	Contact your local ON Semiconductor Sales Office or < jun.hasunuma@onsemi.com>												
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>												
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.												
Change Part Identification:	Affected products will be identified with date code.												
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____												
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____												
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines <input type="checkbox"/> External Foundry/Subcon site(s)												
Description and Purpose:													
This is the Final Process Change Notification to inform customers of the conversion of the Gold wire connecting chip and Lead to Copper wire for LV8702V. Mold resin will be changed to be suitable for Copper wire.													
	<table border="1"> <thead> <tr> <th></th><th>Before Change</th><th>After Change</th></tr> <tr> <th>Material to be changed</th><th>Description</th><th>Description</th></tr> </thead> <tbody> <tr> <td>Wire</td><td>Gold wire</td><td>Copper wire</td></tr> <tr> <td>Mold resin</td><td>GE-1030FK-T</td><td>CV8210AN</td></tr> </tbody> </table>		Before Change	After Change	Material to be changed	Description	Description	Wire	Gold wire	Copper wire	Mold resin	GE-1030FK-T	CV8210AN
	Before Change	After Change											
Material to be changed	Description	Description											
Wire	Gold wire	Copper wire											
Mold resin	GE-1030FK-T	CV8210AN											
There will be no change on the electrical characteristic specifications of the product.													

**Reliability Data Summary:**

QV DEVICE NAME : LV5236VZ

PACKAGE : SSOP44J(275mil)

Test	Specification	Condition	Interval	Results
HTOL	EIAJ ED-4701/100	Tj=Tjmax, Vcc=Operatingmax	1000 hrs	0/22
THB*	EIAJ ED-4701/100	85°C, 85% RH, Vcc=recommended	1000 hrs	0/22
TC*	EIAJ ED-4701/100	Ta= -65°C to +150°C	100 cyc	0/22
AC*	EIAJ ED-4701-3	Ta=121°C ,RH=100% ,205kPa	50 hrs	0/22
HTSL	EIAJ ED-4701/200	Ta= 150°C	1000 hrs	0/22
RSH	EIAJ ED-4701/300	Ta = 255°C , 10 sec (peak 260°C)	2times	0/22

Notes:

The test items with * mark are put into operation after the reflow soldering (at 255°C for 10seconds)

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of affected Standard Parts:

Part Number	Qualification Vehicle
LV8702V-TLM-H	LV5236VZ